Chips Act 2.0 and the future of global collaborations

Opening remarks by session chair

C. Frieling
Director Advocacy and Public Policy
SEMI Europe, Brussels, Belgium

Abstract
Opening remarks by session chair

Biography
Christopher Frieling is Director for Advocacy and Public Policy and Head of office at the SEMI Europe Brussels Office. He has a background in EU affairs, innovation, and tech policy. Mr. Frieling has 15+ years of experience in Brussels and leads SEMI's team for advocay and oversees all of SEMI's engagement in European projects. Prior to SEMI he worked at the Brussels office of Fraunhofer in several roles including most recently as Senior Advisor. Mr. Frieling holds an MSc in Economics of Science and Innovation and a Bachelor of Business Administration.

References

Chips Act 2.0: Building Europe's Trusted Semiconductor Alliances

M. Sweers
Vice Minister
Ministry of Foreign Affairs of the Netherlands,
Foreign Trade, The Hague, The Netherlands

Abstract
Presenting the strategy of The Netherlands in the context of interantional cooperation on semiconductors, starting from the ongoing Chips Act 2.0 negotiations and the potential to expand technological partnerships with trusted partners (South Korea, Taiwan, Japan and Malaysia).

Biography
Michiel Sweers is Vice Minister for Foreign Trade of the Netherlands at the Ministry of Foreign Affairs. He previously served as Director-General for Foreign Economic Relations, overseeing Dutch international trade policy, economic diplomacy and efforts to strengthen the country's global competitiveness.

References



S. Ramundo Orlando
Advocacy Manager
SEMI Europe, Advocacy, Brussels, Belgium

A. Zwegers
Deputy Head of Unit, DG CONNECT
European Commission, DG CONNECT, Brussels, Belgium
O. Schenk
Member of the European Parliament, Rapporteur on the Chips Act 2.0
European Parliament, Committee on Industry, Research and Energy, Brussels, Belgium
G. Fagas
Director
Tyndall National Institute, Executive Leadership Team, Dublin, Ireland
B. Ernst
Senior Vice President
Merck Group, Electronics, Zwingenberg, Germany
F. Le Greves
President
ST Microelectronics, Paris, France
S. Seng
Global Head of Public Affairs
ASM International, Public Affairs, Phoenix, United States of America

Biography
As Europe moves towards the implementation of the **Chips Act 2.0**, strengthening international partnerships will be essential to building a more resilient, secure and competitive semiconductor ecosystem. Europe's position across the semiconductor value chain depends not only on strengthening domestic capabilities, but also on deeper cooperation with trusted partners, including the **US, Japan, Taiwan and South Korea**.

This session will examine how the Chips Act 2.0 can reinforce Europe's strategic positioning and translate international partnerships into practical cooperation on **supply chain resilience, technology, investment and innovation**. It will also explore the role of initiatives such as **ICOS** in connecting European capabilities with trusted international ecosystems.

References

Chips Act 2.0: How can Europe turn semiconductor excellence into investment, scale and resilience?



O. Schenk
Member of the European Parliament, Dresden, Germany

Abstract
Europe has many of the ingredients for semiconductor leadership: world-class research, strong industrial clusters and global champions in critical parts of the value chain. Yet too often, Europe struggles to turn these strengths into investment, scale and new industrial capacity. As the European Parliament begins to shape its position on Chips Act 2.0, the debate must therefore go beyond individual fabs, funding targets and market shares. The real challenge is to build a stronger European semiconductor ecosystem: connecting clusters across borders, bringing research faster to market, mobilising private investment and developing capabilities where strategic dependencies remain. With AI transforming the global geopolitical landscape at unprecedented speed, Europe must decide where it wants to lead, where it needs greater resilience and what it will take to remain a strong global technology player. Chips Act 2.0 is an opportunity to make those strategic choices.

Biography
Oliver Schenk has been a Member of the European Parliament since 2024 and serves as rapporteur in the Committee on Industry, Research and Energy for the Chips Act 2.0. In this role, he is leading the Parliament's work on Europe's future semiconductor policy. Before entering the European Parliament, he served from 2017 to 2024 as a Minister of State in Saxony and Head of the Saxon State Chancellery, including responsibility for European and federal affairs. Over the course of his career, he has held senior positions in both state and federal government, including in the fields of policy planning, digitalisation and technology. His work focuses on strengthening Europe's industrial competitiveness and technological resilience.

References

Panelist



F. Le Grevès
President France & EVP Europe and France Public Affairs
STMicroelectronics, Paris, France

Abstract
Coming Soon

Biography
Frédérique Le Grevès is STMicroelectronics' Executive Vice President, Europe and France Public Affairs. She has also held the position of President of STMicroelectronics France since March 2021.

In 1990, Le Grevès started her career in marketing and communication for various international companies in Europe and in the US. From 1995 to 2003, she worked at Aptiv (ex-Delphi Automotive) as EMEA Communication Director. In 2003, Le Grevès joined Nissan Motors as VP Communication for Europe and in 2004, she moved to Los Angeles as VP Communications for Nissan Americas. Le Grevès returned to France in 2008 and joined the Renault Group as Global VP for Corporate Communication. Two years later, she expanded her role to Global VP of Communications and Deputy to the Chief Marketing and Communication officer. In 2011, Le Grevès was appointed Chief of Staff for the Renault Nissan Mitsubishi Alliance Chairman and CEO. More recently, she worked as senior advisor for several companies helping on corporate effectiveness, operations efficiency, and brand reputation.

Le Grevès has been an independent board member of the Supervisory Board of TRIGO Holding from May 2021 to December 2024 and sat on the Strategic Board of Clinatec since October 2021. She is also an independent Director of the Supervisory Board of North Atlantic (formerly Esso SAS) and became a member of their audit committee in June 2024. In 2022, Le Grevès was appointed President of the Strategic Committee for the Electronics Industry sector in France, and in June 2025 became President of the newly created French Electronics Federation (FdEF). She has also been Vice President of the European Semiconductor Industry Association (ESIA) since 2023. Le Grevès was promoted Knight of the Legion of Honor by the French Ministry of Economy and Finance in January 2023.
Born in Suresnes, France, in 1967, Frédérique Le Grevès graduated with a master's degree in business management from the Paris School of Business (1991) and graduated from the Senior Executive Program at the London Business School (2019).

References

Advanced Packaging: Redefining the New Front End Through Materials Innovation



B. Ernst
SVP and Head of Strategy and Transformation
Merck KGaA, Darmstadt, Germany

Abstract
As semiconductor demand driven by AI continues to increase and traditional scaling methods near their limits, the trends toward advanced chip architectures and 3D densification are accelerating. The traditional boundary between front-end wafer fabrication and back-end assembly is increasingly blurring. Advanced packaging has become the “new front end,” where performance, power
efficiency, yield, and reliability are determined by processes and materials that increasingly resemble those used in the most advanced logic manufacturing environments, powered by the same fundamentals.
Feature sizes in advanced packaging are still relatively large today, but hybrid bonding is changing, driving miniaturization and complexity. It must be approached with the same level of process control, materials sophistication, metrology, and systems understanding that have defined front-end semiconductor manufacturing for decades. Merck’s integrated materials-and-systems solutions will be at the heart of it.
Europe has a unique opportunity to establish a strong position in advanced packaging. Building on its world-class semiconductor ecosystem—including leaders in equipment, process technologies, and innovation. Europe is well positioned to accelerate the next wave of semiconductor advancement through advanced packaging technologies.
In this keynote, Merck will share its perspective on how materials innovation is becoming a key enabler of advanced packaging growth. Critical materials including CMP slurries, cleaning solutions, thin-film deposition materials, and other specialty chemistries must now address challenges.
We will explore how front-end manufacturing experience provides a critical foundation for solving advanced packaging challenges, what differentiates packaging materials development from traditional front-end applications, and how collaborative innovation across the European semiconductor ecosystem can create a sustainable competitive advantage. As advanced packaging becomes a strategic driver of semiconductor performance, Europe has a timely opportunity to shape its
future, and materials innovation will be at the center of that journey.

Biography
Benedikt Ernst is the SVP and Head of Strategy and Transformation at the Electronics business of Merck KGaA, Darmstadt, Germany. As a member of the Electronics Executive Committee, he is responsible for the end-to-end strategic development and transformation of the business sector, encompassing market competitive intelligence, strategic roadmap, business transformation programs, and business and portfolio development. He joined Merck KGaA, Darmstadt, Germany in 2006, and has had various management positions. Since 2018, he has been heading Strategy and Business Development for Electronics and Semiconductor. Before he was Commercial Director for the Semiconductor business and Head of Packaging Business Field.
Benedikt Ernst studied physics at the Technical University of Munich and at the Max Planck Institute of Plasma Physics.

References

Chips Act 2.0 – Building Europe's Trusted Semiconductor Alliances

S. Seng
Global Head of Government Affairs
ASM International, Public Affairs, Phoenix, United States of America

Abstract
ASM International is committed to fostering international technological partnerships to strengthen Europe's semiconductor ecosystem, enhance supply chain resilience, and drive innovation across the semiconductor value chain.

Biography
Seraphina Seng is Global Head of Government Relations and Community Affairs at ASM, operating within the CEO Office. In this strategic role, she leads global public policy engagement and strategic initiatives to strengthen ASM's reputation in key markets, positioning the company as a trusted community and economic partner aligned with its long-term business goals.

With almost 20 years of experience across the public and private sectors, she has built a career at the intersection of government, technology, and international relations, holding leadership and strategic roles at the Singapore Economic Development Board, Applied Materials, and Temasek International, where she most recently served as Vice President of International Relations managing ecosystem engagements across Europe, Northeast Asia and SIngapore.

References

ICOS²: Driving International Cooperation on Semiconductors

G. Fagas
Director of Strategic Development
Tyndall National Institute, Cork, Ireland

Abstract
As Europe shapes a potential Chips Act 2.0, trusted international partnerships will be essential for strengthening resilience, competitiveness, and technological leadership. ICOS² (International Cooperation on Semiconductor Innovation and Supply Resilience) is a Horizon Europe initiative designed to support this ambition by providing evidence-based insights and strategic recommendations to inform European semiconductor policy and cooperation with key global partners.

This presentation will highlight how ICOS² identifies opportunities for collaboration with leading semiconductor ecosystems, helping Europe build more resilient supply chains, accelerate innovation, and reinforce its position in the global value chain. The presentation will also discuss how ICOS² can contribute to the implementation of a future Chips Act 2.0 by providing practical pathways for international engagement, joint research and innovation activities, talent exchange, and strategic industrial cooperation.

Biography
Pr Giorgos Fagas (PhD, MBA) is Director of Strategic Development at Tyndall National Institute and a member of its Executive Leadership Team, where he shapes the institute's international strategy and leads major cross-cutting initiatives. An expert in advanced semiconductors, nanoelectronics and quantum technologies, he has played a central role in European research and innovation, contributing to Ireland's Silicon Island strategy and the EU Chips Act through the implementation of pilot lines such as FAMES, horizon scanning and coordinating numerous EU-funded projects. Advancing international collaboration, expanding pilot line activities, and driving technology foresight efforts that strengthen Europe's semiconductor ecosystem and global partnerships, Giorgos is the Director of SiNANO and coordinator of the ICOS^2 EU Coordination and Support Action on 'International Cooperation on Semiconductor Innovation and Supply Resilience'.

References